

Title (en)

METHOD FOR PRODUCING A MULTILAYER PRINTED CIRCUIT BOARD

Title (de)

VERFAHREN ZUM HERSTELLEN EINER MEHRLAGIGEN LEITERPLATTE

Title (fr)

PROCEDE DE FABRICATION D'UNE CARTE DE CIRCUITS IMPRIMES MULTICOUCHE

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Application

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Abstract (en)

[origin: WO0041447A1] The invention relates to a method for producing a multilayer printed circuit board which is produced by bonding laminate layers (20, 30, 40, 50) which each consist of a conductor layer (24, 25, 31, 32) and an insulating layer (16, 17; 28, 29) to a laminate core (10). According to the invention the via holes (33, 34) between the conductor layers (24, 32 and 25, 31) are formed by laser drilling through the individual laminate layers (40, 50) and then plated through.

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IPC 8 full level

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